

## **DMG1013T-VB Datasheet**

# P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)	Q <sub>g</sub> (TYP.) (nC)			
	0.450 at V <sub>GS</sub> = -4.5 V	-0.55				
-20	0.500 at V <sub>GS</sub> = -2.5 V	-0.50	1			
	0.600 at V <sub>GS</sub> = -1.8 V	-0.38				

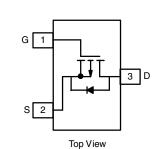
#### **FEATURES**

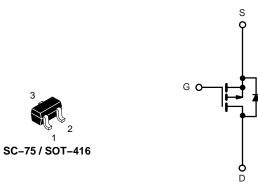
- Trench power MOSFET
- 100 % R tested
- Fast switching speed



#### **APPLICATIONS**

- Load / power switch for portable devices
- Drivers: relays, solenoids, displays
- Battery operated systems





P-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>A</sub> = 25 °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V <sub>DS</sub>	-20	V
Gate-Source Voltage		V <sub>GS</sub>	± 12	V
0 11	T <sub>A</sub> = 25 °C		-0.55 <sup>b, c</sup>	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 70 °C	I <sub>D</sub>	-0.45 <sup>b, c</sup>	
Pulsed Drain Current (t = 300 μs)		I <sub>DM</sub>	-1.8	A
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	-0.16 <sup>b, c</sup>	
Maximum Dayler Dissination	T <sub>A</sub> = 25 °C	В	0.19 <sup>b, c</sup>	10/
Maximum Power Dissipation	T <sub>A</sub> = 70 °C	P <sub>D</sub>	0.12 <sup>b, c</sup>	W
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	-55 to +150	°C

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum Junction-to-Ambient <sup>a, b</sup>	t ≤ 5 s	Б	440	530	°C/W	
waximum sunction-to-Ambient 4, 2	Steady State	$R_{thJA}$	540	650	C/VV	

#### Notes

- a. Maximum under steady state conditions is 650  $^{\circ}\text{C/W}.$
- b. Surface mounted on 1" x 1" FR4 board.
- $c. \ t=5 \ s.$

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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static				•		•	
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0$ , $I_D = -250 \mu A$	-20	-	-	V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 A	-	-12	-	mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = -250 μA	-	1.8	-		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-0.4	-	-1	V	
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 8 V	-	-	± 30		
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$	-	-	± 1		
Zoro Goto Voltago Drain Current	l	V <sub>DS</sub> = -20 V, V <sub>GS</sub> = 0 V	-	-	-1	— μA —	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 85 °C	-	-	-10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = \ge 5 \text{ V}, V_{GS} = -4.5 \text{ V}$	-1.5	-	-	Α	
		$V_{GS} = -4.5 \text{ V}, I_D = -0.4 \text{ A}$	-	0.450	-		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = -2.5 \text{ V}, I_D = -0.2 \text{ A}$	-	0.500	-	Ω	
		V <sub>GS</sub> = -1.8 V, I <sub>D</sub> = -0.1 A	-	0.600	-	<u> </u>	
Forward Transconductance	9fs	$V_{DS} = -10 \text{ V}, I_D = 0.4 \text{ A}$	-	1	-	S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>		-	45	1	pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	15	1		
Reverse Transfer Capacitance	$C_{rss}$		-	10	1		
Total Gate Charge	Qg	$V_{DS}$ = -10 V, $V_{GS}$ = -4.5 V, $I_D$ = -0.4 A	-	1.65	2.50		
			-	1	2	nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS}$ = -0 V, $V_{GS}$ = -2.5 V, $I_D$ = -0.4	-	0.2	1	110	
Gate-Drain Charge	$Q_{gd}$		-	0.26	1		
Gate Resistance	$R_g$	f = 1 MHz	2.4	12	24	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>		-	9	18		
Rise Time	t <sub>r</sub>	$V_{DD}$ = -10 V, $R_L$ = 33.3 $\Omega$	-	10	20		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D\cong$ -0.3 A, $V_{GEN}=$ -4.5 V, $R_g=$ 1 $\Omega$	-	10	20		
Fall Time	t <sub>f</sub>		-	8	16	ne	
Turn-On Delay Time	t <sub>d(on)</sub>		_	1	2	ns	
Rise Time	t <sub>r</sub>	$V_{DD}$ = -10 V, $R_L$ = 33.3 $\Omega$	-	8	16	]	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D\cong$ -0.3 A, $V_{GEN}=$ -8 V, $R_g=$ 1 $\Omega$	-	9	18		
Fall Time	t <sub>f</sub>		-	5	10		
<b>Drain-Source Body Diode Characteris</b>	tics						
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>		-	_	-1.5	А	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = -0.3 A	-	-0.8	-1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>		-	16	24	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	1 0 2 0 41/-4 400 0/	-	8	16	nC	
Reverse Recovery Fall Time	ta	I <sub>F</sub> = -0.3 A, dI/dt = 100 A/μs	-	11	-		
Reverse Recovery Rise Time	t <sub>b</sub>			5	-	ns	

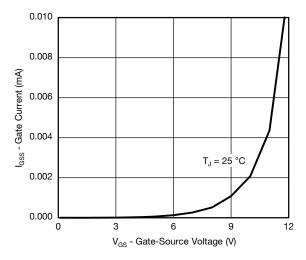
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

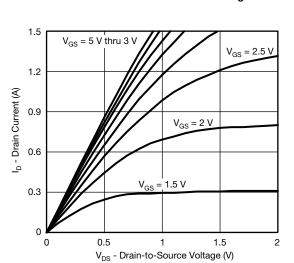
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



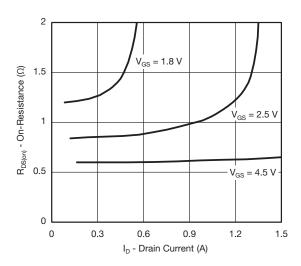
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



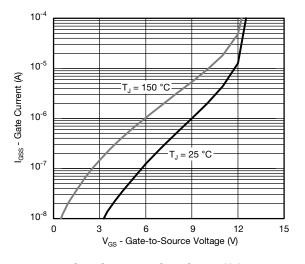
**Gate Current vs. Gate-Source Voltage** 



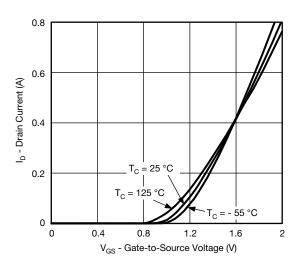
**Output Characteristics** 



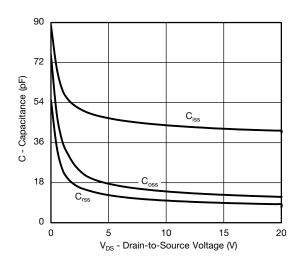
On-Resistance vs. Drain Current



**Gate Current vs. Gate-Source Voltage** 



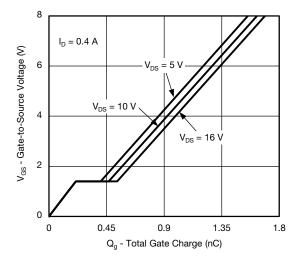
**Transfer Characteristics** 



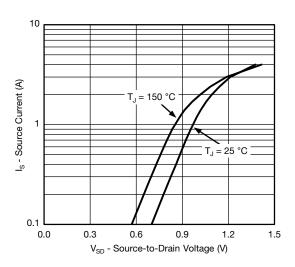
Capacitance



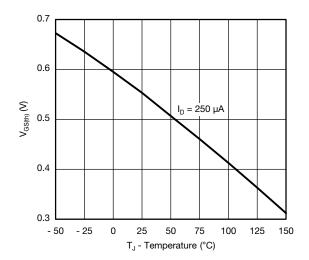
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



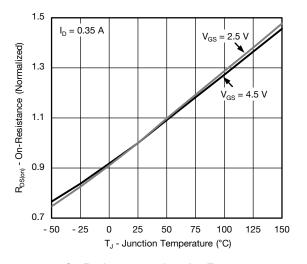
**Gate Charge** 



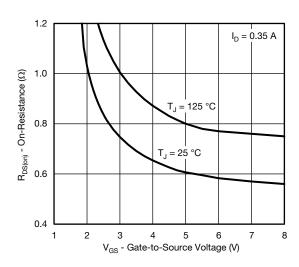
Source-Drain Diode Forward Voltage



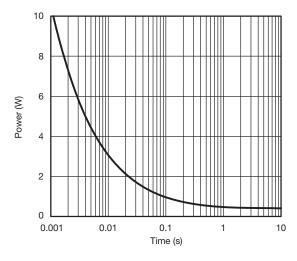
**Threshold Voltage** 



On-Resistance vs. Junction Temperature



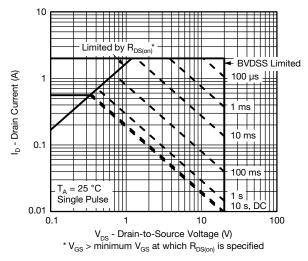
On-Resistance vs. Gate-to-Source Voltage

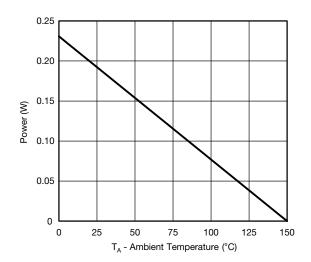


Single Pulse Power, Junction-to-Ambient



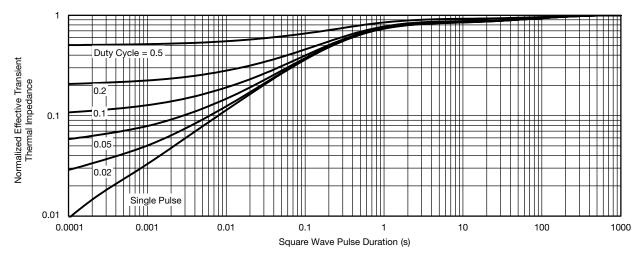
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Safe Operating Area, Junction-to-Ambient

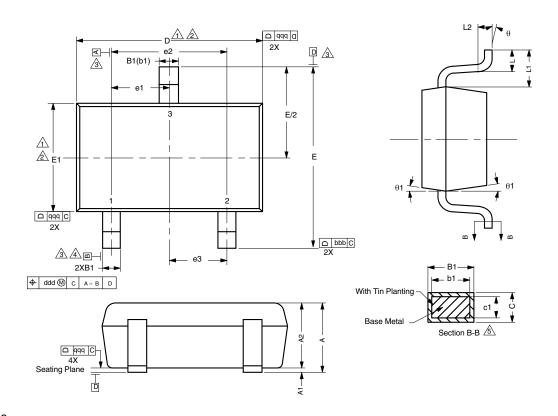
Power Derating, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient



## **SC-75: 3 Leads**



DWG: 5868

#### **Notes**

Dimensions in millimeters will govern.

⚠Dimension D does not include mold flash, protrusions or gate burrs. Mold flash protrusions or gate burrs shall not exceed 0.10 mm per end. Dimension E1 does not include Interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.10 mm per side.

Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body.

Datums A, B and D to be determined 0.10 mm from the lead tip.

Terminal positions are shown for reference only.

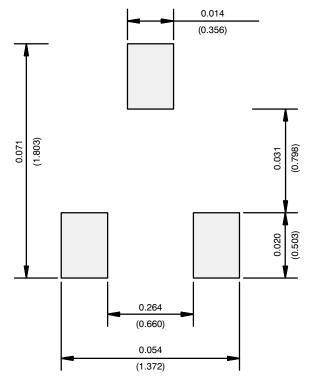
These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIMENSIONS	TOLERANCES	
aaa	0.10	
bbb	0.10	
ccc	0.10	
ddd	0.10	

DIM.	MIN.	NOM.	MAX.	NOTE
Α	-	-	0.80	
A1	0.00	-	0.10	
A2	0.65	0.70	0.80	
B1	0.19	-	0.24	5
b1	0.17	-	0.21	
С	0.13	-	0.15	5
c1	0.10	-	0.12	5
D	1.48	1.575	1.68	1, 2
E	1.50	1.60	1.70	
E1	0.66	0.76	0.86	1, 2
e1		0.50 BSC		
e2	1.00 BSC			
e3	0.50 BSC			
L	0.15	0.205	0.30	
L1	0.40 ref.			
L2	0.15 BSC			
q	0°	-	8°	
q1	4°	-	10°	



### **RECOMMENDED MINIMUM PADS FOR SC-75: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)

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